

Conductive Form-In-Place Gasket

F5305



Description

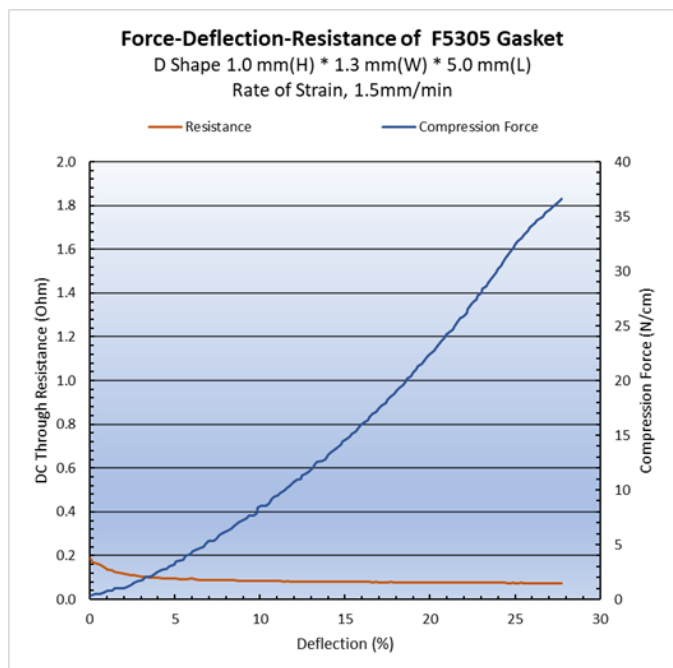
The F5305 is a highly compressible Form-in-Place gasket. With extremely high conductivity, this material provides superior shielding effectiveness at a much softer compression level.

This material is preferable for large metal housings with extensive tolerance variations.

The F5305 is designed for large profile applications, (e.g. bead size from 0.9mm (0.035") to 3.0mm (0.120") on metal substrates).

Benefits

- Extremely High Conductivity in the Ni/Gr filled FIP line
- A highly compressible soft gasket designed for low compression force applications
- More than 100 dB shielding effectiveness from 200 MHz to 40GHz with a small gasket bead
- More than 80 Newtons/cm² shear adhesion on common housing substrates and coatings



Properties	Unit	F5305
Elastomer Binder		Silicone
Conductive Filler		Ni/Gr
Cure System		Thermal
Density	g/cm ³	1.8
Hardness	Shore A	40
Adhesion on Al metal	N/cm ²	80
Tensile Strength	psi	150
Elongation	%	100
Tear Strength	lb/in	50
Temperature Range	°C	-45 to 150
Maximum Using Temperature	°C	200
UL Flammability Rating	UL94 V-0	E303387
DC-Through Resistance @30% compression, 1mmH	Ohm	0.08
Shielding Effectiveness 200 MHz – 40 GHz	dB	>100



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